

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) A method of breaking a substrate of brittle material, the method comprising acts of:

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providing a substrate of a brittle material,

heating the substrate with a laser beam to create a heated spot on the substrate,

moving the laser beam and the substrate with respect to each other to create a line of heated spots on the substrate,

cooling the heated spots on the substrate by locally applying a cooling medium such that a micro-crack in the line of heated spots is propagated on the substrate, and

breaking the substrate along the line of the propagated micro-crack by applying a force on the substrate

wherein the cooling medium comprises an aqueous surfactant solution.

2. (Currently amended) The method of breaking a substrate of brittle material according to claim 1, wherein the cooling medium further comprises air mixed with the aqueous surfactant solution.

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3. (Currently amended) The method of breaking a substrate of
brittle material according to claim 1, wherein the concentration of
the surfactant is in the range of 0.01 to 1% of weight.

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4. (Currently amended) The method of breaking a substrate of
brittle material according to claim 1, wherein the aqueous
surfactant solution comprises a cationic surfactant.

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5. (Currently amended) The method of breaking a substrate of
brittle material according to claim 4, wherein the cationic
surfactant comprises cetyl trimethyl ammonium bromide (CTAB).

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6. (Currently amended) The method of breaking a substrate of
brittle material according to claim 1, wherein the aqueous
surfactant solution comprises a nonionic surfactant.

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7. (Currently amended) The method of breaking a substrate of
brittle material according to claim 6, wherein the nonionic
surfactant comprises octadecyl deca(ethyleneoxide) hydroxide.

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8. (Currently amended) The method of breaking a substrate of
brittle material according to claim 1, wherein the aqueous
surfactant solution comprises an anionic surfactant.

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9. (Currently amended) ~~The method of breaking a substrate of brittle material according to claim 2, wherein the anionic surfactant comprises dodecylbenzene sulfonic acid sodium salt.~~

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10. (Currently amended) ~~The method of breaking a substrate of brittle material according to claim 1, wherein the brittle material comprises one or more of glass, crystalline silica and ceramics.~~

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11. (New) A method of breaking a substrate of brittle material, the method comprising acts of:

providing a substrate of a brittle material,

heating the substrate with a laser beam to create a heated spot on the substrate,

moving the laser beam and the substrate with respect to each other to create a line of heated spots on the substrate,

cooling the heated spots on the substrate by locally applying an aqueous surfactant solution such that a micro-crack in the line of heated spots is propagated on the substrate and the aqueous surfactant solution enters the micro-crack, and

breaking the substrate along the line of the propagated micro-crack by applying a force on the substrate, wherein the aqueous surfactant solution enters the micro-crack prior to the breaking act.

12. (New) The method of breaking a substrate of brittle material according to claim 11, wherein the aqueous surfactant solution is selected to bond to broken substrate bonds in the micro-crack.

13. (New) The method of breaking a substrate of brittle material according to claim 11, wherein the aqueous surfactant solution further comprises air mixed with the aqueous surfactant solution.

14. (New) The method of breaking a substrate of brittle material according to claim 11, wherein the concentration of the aqueous surfactant solution is in the range of 0.01 to 1% of weight.

15. (New) The method of breaking a substrate of brittle material according to claim 11, wherein the aqueous surfactant solution comprises a cationic surfactant.

16. (New) The method of breaking a substrate of brittle material according to claim 15, wherein the cationic surfactant comprises cetyl trimethyl ammonium bromide (CTAB).

17. (New) The method of breaking a substrate of brittle material according to claim 11, wherein the aqueous surfactant solution comprises a nonionic surfactant.

18. (New) The method of breaking a substrate of brittle material according to claim 17, wherein the nonionic surfactant comprises octadecyl deca(ethylenoxide) hydroxide.

19. (New) The method of breaking a substrate of brittle material according to claim 11, wherein the aqueous surfactant solution comprises an anionic surfactant.

20. (New) The method of breaking a substrate of brittle material according to claim 19, wherein the anionic surfactant comprises dodecylbenzene sulfonic acid sodium salt.